# 650V, 38A, 61mΩ N-channel Power Super Junction MOSFET

## JMH65R070PSFD

#### **Features**

- $\bullet \;\;$  Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant

# **Product Summary**

Parameters	Value	Unit
V <sub>DSS</sub>	650	V
$V_{GS(th)\_Typ}$	3.9	٧
I <sub>D</sub> (@V <sub>GS</sub> =10V)	38	Α
$R_{DS(ON)\_Typ}(@V_{GS}=10V$	61	mΩ

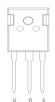


#### **Applications**

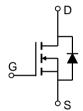
- SMPS with PFC,
- Flyback and LLC topologies
- Silver ATX,adapter,TV,lighting,Telecom



TO-247 Top View



**Pin Assignment** 



**Schematic Diagram** 

#### **Ordering Information**

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
JMH65R070PSFD-U	65R070PF	N/A	Tape&Reel	TO-247-3L	30	2250

### Absolute Maximum Ratings (@ T<sub>C</sub> = 25°C unless otherwise specified)

	<u> </u>	<u></u>	•	
Symbol	Parameter		Value	Unit
V <sub>DS</sub>	Drain-to-Source Voltage		650	V
$V_{GS}$	Gate-to-Source Voltage		±30	V
1	Continuous Drain Current	$T_C = 25^{\circ}C$	38	۸
I <sub>D</sub>	Continuous Drain Current	$T_C = 100$ °C	24	— A
$I_{DM}$	Pulsed Drain Current (1)		Refer to Fig.4	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energ	gy <sup>(2)</sup>	461	mJ
P <sub>D</sub>	Power Dissipation	$T_C = 25^{\circ}C$	269	W
		$T_C = 100$ °C	108	VV
$T_{J}$ , $T_{STG}$	Junction & Storage Temperature Range		-55 to 150	°C

#### **Thermal Characteristics**

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	42	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.5	C/ VV



### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

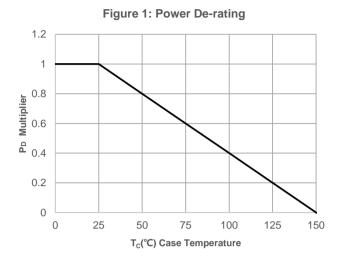
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics			ı		ı
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	650	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	-	-	10.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 30V$	-	-	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.7	3.9	5.1	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance (4)	$V_{GS} = 10V, I_D = 24A$	-	61	70	mΩ
Dynam	ic Characteristics					
$R_g$	Gate Resistance	f = 1MHz	-	1.9	-	Ω
C <sub>iss</sub>	Input Capacitance	\	2429	3401	4591	pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 325V,$ f = 1MHz	56	78	105	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 – 1101112	-	7.7	-	pF
$Q_g$	Total Gate Charge		50	70	95	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 325V, I_D = 24A$	18	25	34	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V DS = 323 V, ID = 2474	19	26	36	nC
0	to a Oh anastariation					
	ing Characteristics			T 70	1	l
t <sub>d(on)</sub>	Turn-On DelayTime		-	78	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 325V$	-	77	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime	$I_D = 24A$ , $R_{GEN} = 24\Omega$	-	174	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	50	-	ns
_	iode Characteristics	_		l .	Γ	I .
I <sub>S</sub>	Maximum Continuous Body Diode Forward Current		-	-	38	А
I <sub>SM</sub>	Maximum Pulsed Body Diode Forward Current		-	-	150	Α
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 24A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 24A, di/dt = 100A/us	194	271	366	ns
Qrr	Body Diode Reverse Recovery Charge	1 <sub>1</sub> = 27A, al/al = 100A/as	-	1446	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2.  $E_{AS}$  condition: Starting  $T_J$ =25C,  $V_{DD}$ =50V,  $V_{GS}$ =10V,  $R_G$ =25ohm, L=10mH,  $I_{AS}$ =9.6A,  $V_{DD}$ =0V during time in avalanche.
- $3.\ R_{ ext{BJA}}$  is measured with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square pad layout.
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



# **Typical Performance Characteristics**



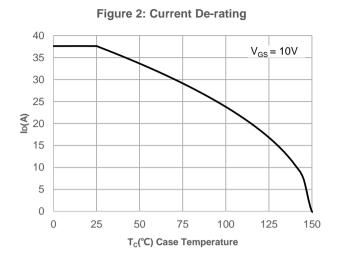
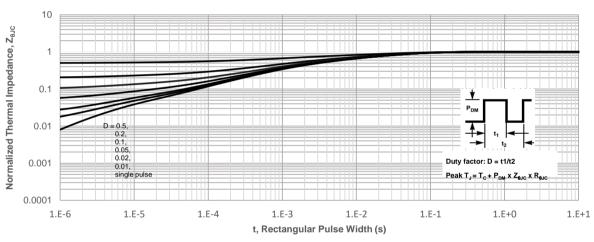


Figure 3: Normalized Maximum Transient Thermal Impedance

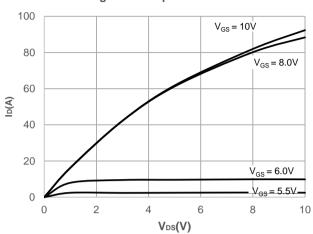


10000  $V_{GS} = 10V$ For TEMPERATURES ABOVE IDM Peak Current(A) 25°C DERATE PEAK CURRENT 1000 150*-Tc* 125 100 Single Pulse 10 1.E-6 1.E-5 1.E-4 1.E-1 1.E+0 1.E+1 1.E-3 1.E-2 t, Rectangular Pulse Width (s)



# **Typical Performance Characteristics**





**Figure 6: Typical Transfer Characteristics** 

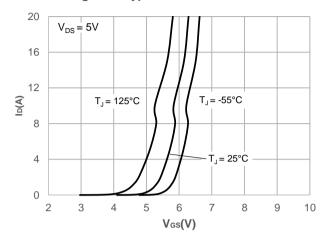


Figure 7: On-resistance vs. Drain Current

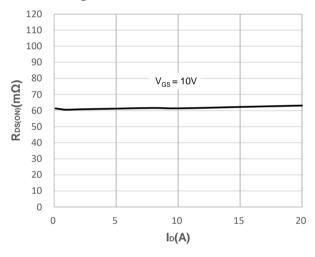


Figure 8: Body Diode Characteristics

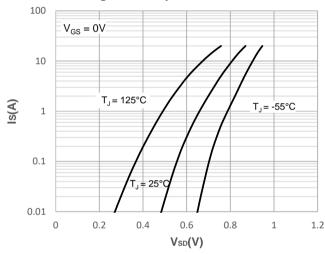


Figure 9: Gate Charge Characteristics

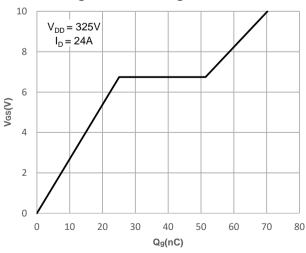
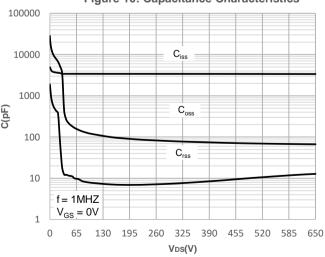


Figure 10: Capacitance Characteristics





# **Typical Performance Characteristics**

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

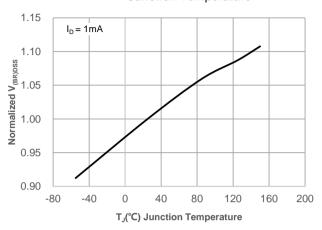


Figure 13: Normalized Threshold Voltage vs.
Junction Temperature

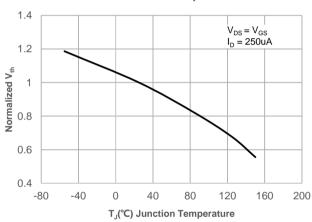


Figure 15: Maximum Safe Operating Area

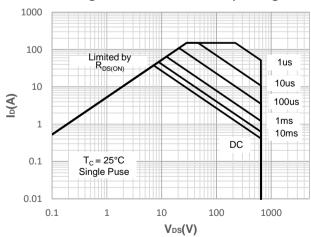
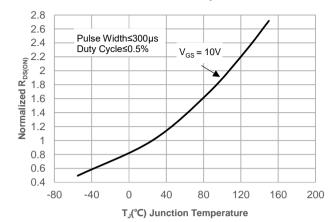
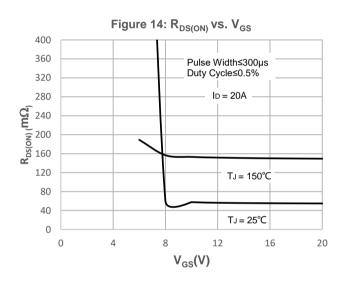


Figure 12: Normalized on Resistance vs.
Junction Temperature







## **Test Circuit**

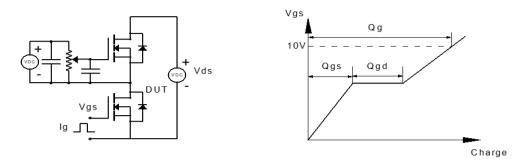


Figure 1: Gate Charge Test Circuit & Waveform

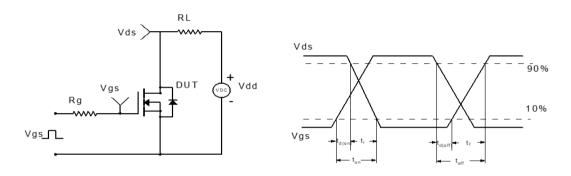


Figure 2: Resistive Switching Test Circuit & Waveform

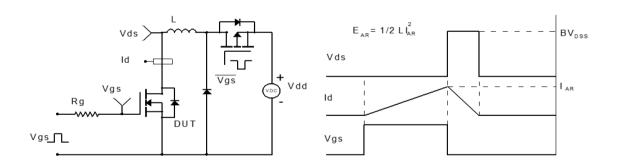


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

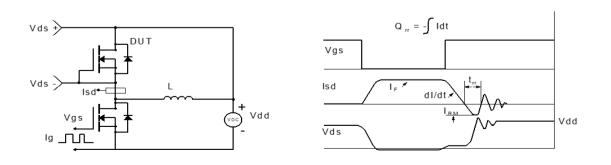
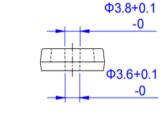


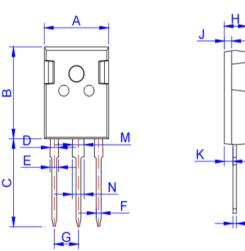
Figure 4: Diode Recovery Test Circuit & Waveform



## Package Mechanical Data(TO-247-3L)

#### **Package Outline**





			Dime	nsions		
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	15.50	15.80	16.10	0.610	0.622	0.634
В	20.80	21.00	21.20	0.819	0.827	0.835
С	19.70	20.00	20.30	0.776	0.787	0.799
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.90	2.10	2.30	0.075	0.083	0.091
F	1.00	1.20	1.40	0.039	0.047	0.055
G	5.25		5.65	0.207		0.222
Н	4.80	5.00	5.20	0.189	0.197	0.205
J	1.90	2.00	2.10	0.075	0.079	0.083
K	2.20	2.35	2.50	0.087	0.093	0.098
L	0.41	0.60	0.79	0.016	0.024	0.031
М	2.80	3.00	3.20	0.110	0.118	0.126
N	2.90	3.10	3.30	0.114	0.122	0.130

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